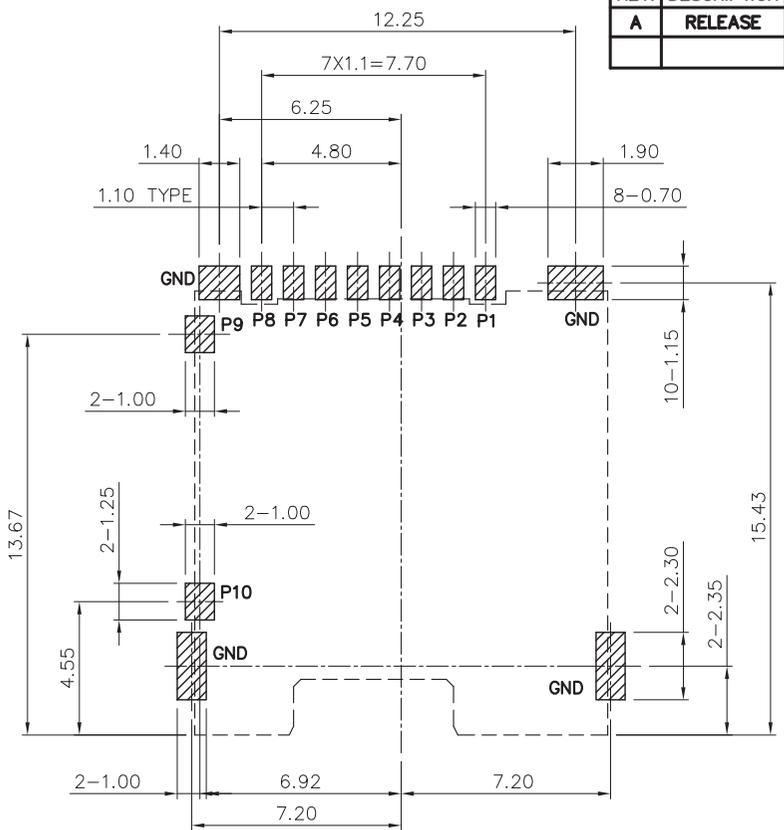
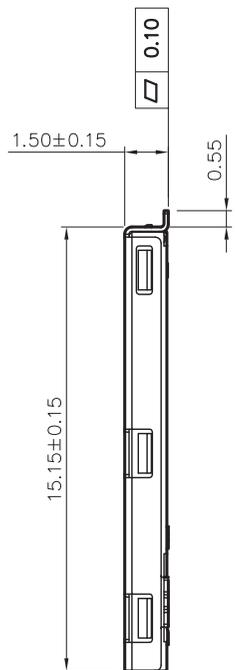
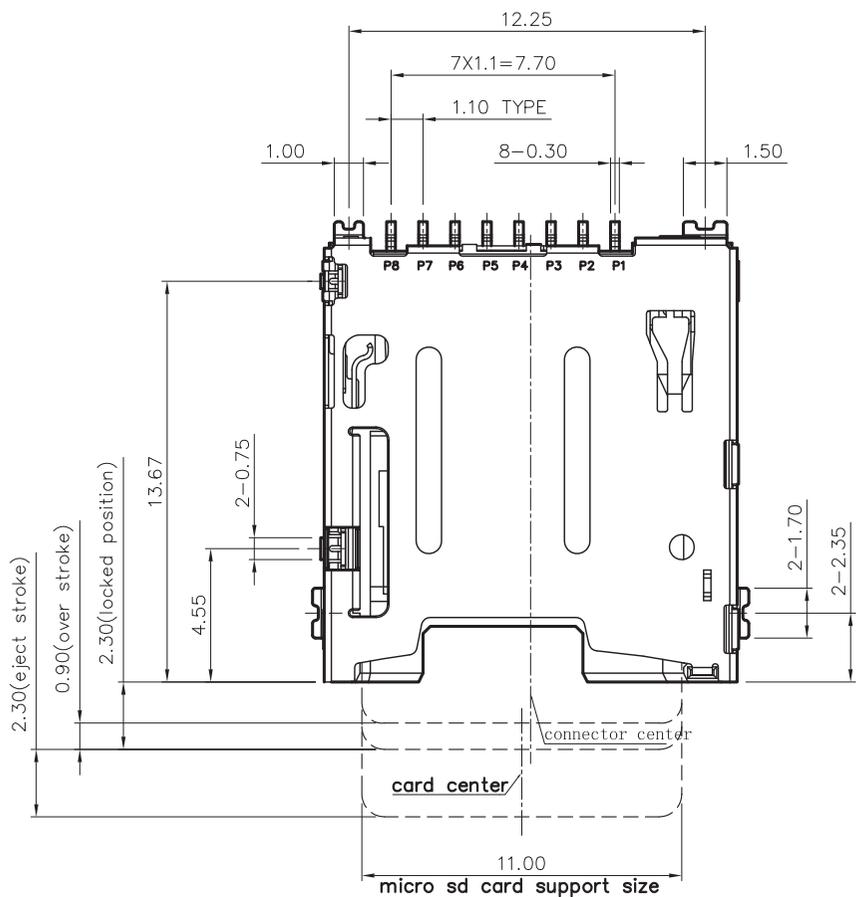
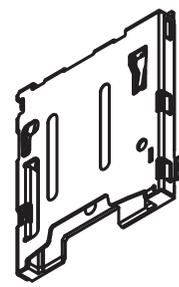
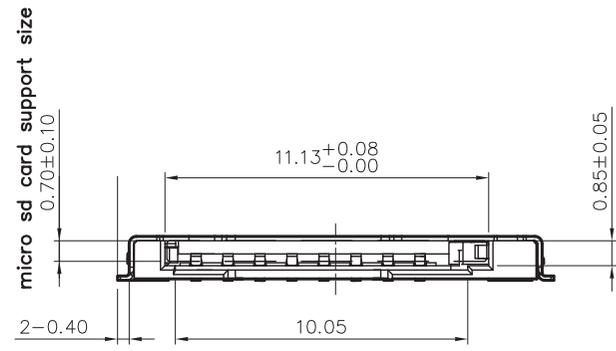


REV.	DESCRIPTION	DATE
A	RELEASE	Mar,08, 2013



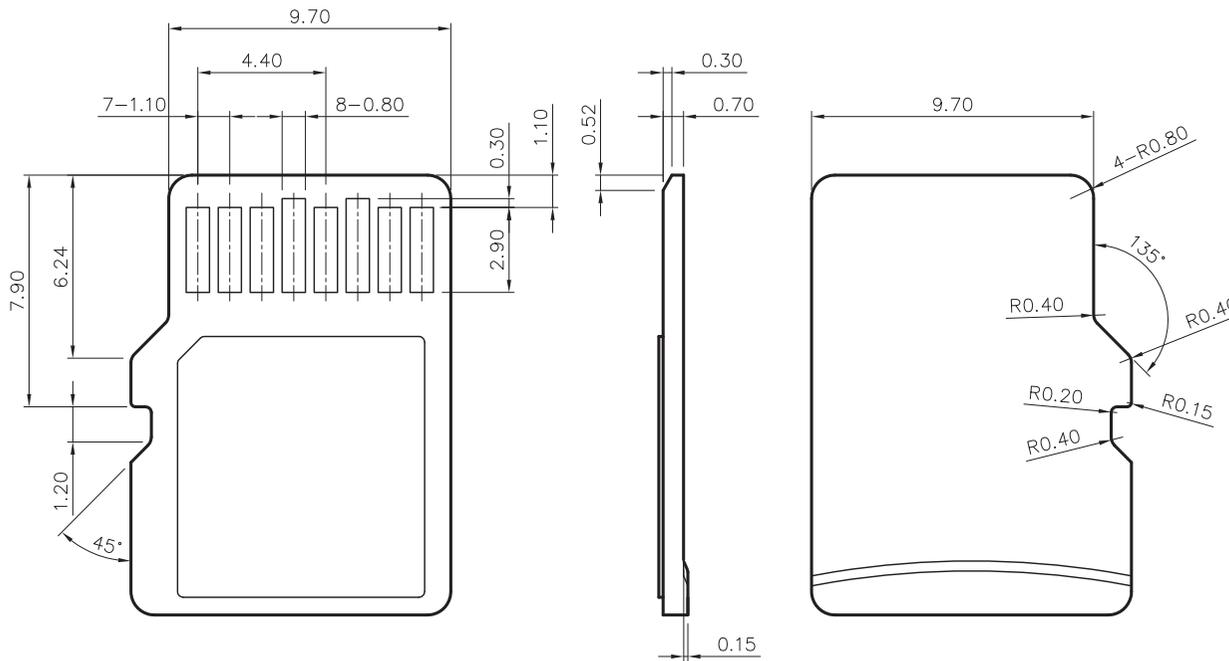
RECOMMEND PCB LAYOUT
TOLERANCE: ±0.05
TOP VIEW



DESCRIPTION OF PLATING ON TERMINALS			
NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"

TOLERANCE .0=±0.25 .00=±0.15 .000=±0.05 ANG.=±3'		DRAWER <i>SU</i> CHECK <i>SU</i> APP'D <i>RAWK</i> PRODUCT SPEC. —		NAME 汉硕电子科技有限公司
UNITS : mm		DRAW NO.		
SCALE NONE	SIZE A8	SHEET 1 OF 2	REV. A	R5109108-X1101S-X

REV.	DESCRIPTION	DATE
A	RELEASE	Mar,08, 2013



MATERIALS

1. HOUSING : THERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY, PLATING SEE TABLE.
3. SHELL : COPPER ALLOY,NICKEL PLATED OVERALL.

SPECIFICATION

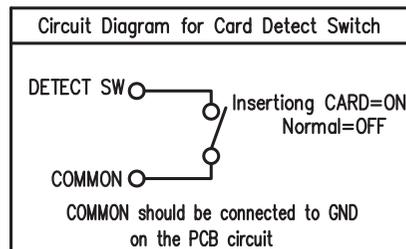
1. CURRENT RATING : 0.5 A. MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE : 500V AC R.M.S. FOR 1 MINUTE.
3. INSULATION RESISTANCE : 1000MΩ MIN.AT 500V DC.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE : -40°C TO +85°C.
6. MATING CYELES : 10000 INSERTIONS.

PART NUMBER INFORMATION :

5109108-X1101S-X

SERIES CODE
SMT 90°
MICRO SD CARD
SINGLE TYPE
NUMBER OF POSITIONS

R:RoHS
H:HALOGEN FREE
FOLLOW NUMBER
WITH PUSH
INSERT TYPE
PLATING SEE TABLE



PIN NO.	discription	DESCRIPTION OF PLATING ON TERMINALS			
		NO.	EXPLAIN	NO.	EXPLAIN
Pin 1	DAT2:Data line	0	GOLD FLASH	3	GOLD 15u"
Pin 2	CD/DAT3:card Detect/Data line	1	GOLD 5u"	4	GOLD 20u"
Pin 3	CMD: command/Response	2	GOLD 10u"	6	GOLD 30u"
Pin 4	VDD: Supply voltage	TOLERANCE .0=±0.25 .00=±0.15 .000=±0.05 ANG.=±3°			
Pin 5	CLK: Clock				
Pin 6	VSS:Supply voltage ground	DRAWER		汉硕电子科技有限公司	
Pin 7	DAT0:Data line	CHECK			
Pin 8	DAT1:Data line	APP'D		NAME	
Pin 9	DETECT SW(GND)	PRODUCT SPEC.		MICRO SD PUSH PUSH 1.5H 8PIN	
Pin 10	DETECT SW(CD)	UNITS : mm		DRAW NO.	
GND	Cover GND	SCALE NONE		R5109108-X1101S-X	
		SIZE A8	SHEET 2 OF 2	REV. A	